

LEOCO CORPORATION	PRODUCTION SPECIFICATION	No.	S-96-2530	Rev	5
* 2530 Series and 2531, 2571 Series Connector *					
<p>This product specification contains the test method, the general performance and requirements for interconnection system connector.</p> <p>With 2530 series socket and 2531, 2571 series header and 2533 series crimp terminal.</p>					
<p>1. Construction and dimensions shall be in accordance with the referenced drawings. 产品结构及尺寸依据所提供的图面.</p> <p>2. Characteristics 特性: Current rating 额定电流: 3 A AC,DC Voltage rating 额定电压: 250V AC,DC Temperature rating 额定温度: -40°C ~ +105°C Applicable wire 适用的线: conductor construction size #22 ~ #28</p> <p>3. Electrical performance 电气性能:</p>					
Item 项目	Description 内容	Test Method & Condition 测试方法及条件	Requirement 需求		
3-1	Contact Resistance 接触阻抗	It should be tested in accordance with method EIA-364-23.	Initial: 20 mΩ max. After environmental Test: 40 mΩ max.		
3-2	Insulation Resistance 绝缘阻抗	It should be tested in accordance with Method EIA-364-21.	Initial: 1000 MΩ min. After humidity test 500 MΩ min.		
3-3	Dielectric Withstanding Voltage 耐电压	Unmated connectors shall be tested in accordance with method EIA-364-20 when the AC 1000 Vrms for one minute applied between adjacent contacts.	No evidence of breakdown and flashover		
4. Mechanical Performance 机械性能 :					
Item 项目	Description 内容	Test Method & Condition 测试方法及条件	Requirement 需求		
4-1	Crimp Tensile Strength 铆合张力强度	Pulling load shall be applied between correctly crimped contact and wire at a constant speed. Pulling speed: 25 mm / minute.	AWG #22: 4.0 kgf min. AWG #24: 2.5 kgf min. AWG #26: 1.5 kgf min. AWG #28: 1.0 kgf min.		
4-2	Contact Insertion Force 接触插入力	The force required to insert a contact into a housing. Inserting speed: 25 mm / minute.	0.65Kgf max.		
4-3	Contact removal Force 接触拔出力	Crimped contact mounted in a housing shall be pulled in an alignment at a constant speed of 25 mm / minute.	2.0Kgf min.		

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4-4	Post Retention Force 保持力	The end of a post shall be pushed in a perpendicular to base housing at a constant speed of 25 mm / minute.	1.0 kgf min.			
4-5	Insertion Force 插入力	Housing with contact mating header at a constant speed of 25 mm / minute.	0.35 kgf max.			
4-6	Withdrawal Force 拔出力	Housing with contact mating header, Pull out from header at speed 25 mm / minute.	0.06 kgf min.			
4-7	Durability 耐久性	It should be tested in accordance with method EIA-364-09 Connector shall be subjected to 100 cycles of insertion and withdrawal.	No defects. Contact resistance shall be 20 mΩ max.			
4-8	Vibration 振动测试	The socket mated header shall be vibrated in accordance with method EIA-364-28. There shall be no current discontinuity longer than 1 microsecond during the test . Frequency: 10-55-10 Hz / min. Amplitude: 1.52mm Period: 2 hours for each direction.	No evidence of loosening of parts or electric discontinuity. Contact resistance initial.			
5. Environmental Performance 环境性能:						
Item 项目	Description 内容	Test Method & Condition 测试方法及条件	Requirement 需求			
5-1	Humidity 耐湿性	The unmated connector shall be tested in accordance with method EIA-364-31. Temperature: 40±2 °C Humidity: 90 ~ 95 % (RH) Period: 96 hours.	NO damage. Contact resistance less than twice of initial. Insulation resistance: to parameters. 3-2. Dielectric withstand ing voltage: to parameters 3-3			
5-2	Salt Spray 盐雾测试	Connector shall be tested in accordance with method 1 EIA-364-26 Temperature: 35±2 °C Density: 5 % in weight. Period: 48 hours.	NO damage. Contact resistance less than twice of initial.			

Item 项目	Description 内容	Test Method & Condition 测试方法及条件	Requirement 需求
5-3	Solderability 着锡性	Connector termination ends shall be checked for solderability in accordance with method EIA-364-52. Solder temperature: 245±5 °C Immersion period: 5±0.5 sec.	NO damage. Minimum: 95 % of immersed area.
5-4	Resistance to Soldering Heat 耐焊锡热	Specimen shall be mounted on PCB. Solder temperature: 260±5 °C Immersion period: 5±0.5 sec.	NO damage and deformation.
		High-temperature materials: Specimen shall be mounted on PCB. Solder temperature: 280±5 °C Immersion period: 5±0.5 sec.	